

# The Transition to Mandated Ternary Architectures via Memristive Hysteresis

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## ABSTRACT

*This paper investigates the architectural and economic feasibility of transitioning from dominant binary CMOS computing to a "Mandated Ternary" paradigm. The proposed system is defined by a physically stable, non-volatile third logic state ("Null" or "Balance") engineered into memristive devices via hysteresis. This third state is not a software convention but a hardware-enforced checkpoint that gates computational actions, providing a novel mechanism for safety, security, and auditability. The central thesis is that this paradigm offers a discontinuous advantage over incremental binary scaling by directly mitigating the most pressing bottlenecks in advanced semiconductor nodes: interconnect delay, the memory wall, and power density. We provide rigorous analysis of device physics, focusing on Tantalum Oxide (TaO<sub>x</sub>) RRAM as a primary example. Our analysis quantifies a substantial "emulation tax"—over 15x in energy and 5x in latency—incurred when simulating ternary logic on binary hardware, thereby motivating native implementations. We argue that the rise of agentic AI, with its need for verifiable, enforceable hesitation, serves as a critical catalyst for this architectural shift. The paper concludes with a roadmap to 2027 for achieving industry-standard viability. The key innovation is the concept of **Hardware-Enforced Hesitation**—a physically un bypassable third state that enables auditable safety mechanisms for autonomous systems.*

**Keywords** Ternary logic, Memristor, RRAM, Compute-in-memory, Agentic AI, Hardware security, Hardware-Enforced Hesitation, Emerging memory technologies.

## 1. INTRODUCTION

The semiconductor industry faces a convergence of physical and economic limits as CMOS scaling approaches its fundamental boundaries [1]. At advanced process nodes (3nm class and beyond), the limitations of binary logic are no longer distant concerns but defining constraints of modern system-on-chip (SoC) design. The relentless pursuit of performance through Moore's Law has encountered barriers that incremental improvements cannot overcome: the interconnect bottleneck, the breakdown of Dennard scaling, and the persistent memory wall [2].

The "Mandated Ternary" architecture, enabled by memristive hysteresis, presents a viable path forward by fundamentally rethinking the basis of digital logic. This paradigm introduces a physically stable, non-volatile third state ("Null") as a hardware-enforced authorization mechanism, providing a discontinuous architectural advantage over incremental binary scaling.

The concept of the memristor was first theorized by Chua in 1971 as the fourth fundamental passive circuit element [3]. The physical realization came in 2008 when Strukov et al. at HP Labs demonstrated the first working memristor device [4]. Since then, various memristive technologies have emerged, with TaOx-based RRAM demonstrating particularly promising characteristics including high endurance exceeding  $10^9$  cycles [5].

This paper makes the following contributions:

1. We quantify the "emulation tax" of implementing ternary logic on binary hardware, demonstrating over 15x energy and 5x latency penalties through rigorous numerical analysis.
2. We establish the physical feasibility of a stable third state in TaOx memristors, analyzing the device physics of filament formation and partial reset mechanisms.
3. We map critical CMOS bottlenecks to specific ternary architectural mechanisms, demonstrating why "just better binary" is insufficient.
4. We identify agentic AI as a key catalyst, where hardware-enforced hesitation provides safety guarantees impossible with software flags.
5. We provide a falsifiable roadmap to 2027 with specific milestones for three candidate architectures.

## 2. DEVICE PHYSICS OF MEMRISTIVE HYSTERESIS

### 2.1 The Ideal Memristor and Physical Realization

The ideal memristor is defined by a constitutive relationship between magnetic flux and electric charge, where the rate of change of flux with respect to charge is a state-dependent function known as the memristance [3]. This leads to a voltage-current relationship where the voltage at any time is proportional to the product of the memristance and the current. A key characteristic is the pinched hysteresis loop in the current-voltage (I-V) plane, which passes through the origin.

The physical discovery by Strukov et al. demonstrated that memristive behavior emerges naturally in nanoscale systems where electronic and ionic transport are coupled under high electric fields [4]. This breakthrough enabled the practical implementation of memristive devices using metal-oxide thin films.

## 2.2 Tantalum Oxide (TaOx) Device Physics

TaOx-based RRAM has emerged as a leading candidate for implementing multi-state logic due to its well-understood switching mechanism and demonstrated ability to support multiple resistance levels. The device typically consists of a metal-insulator-metal (MIM) stack, where a thin layer of tantalum oxide is sandwiched between two metal electrodes.

*Device Stack Archetype:* The archetypal high-performance TaOx memristor consists of a carefully engineered bilayer stack [5]. The structure includes:

- Bottom electrode (BE): typically inert metal such as Platinum (Pt).
- Bilayer oxide: thin, highly insulating  $\text{Ta}_2\text{O}_{5-x}$  layer (~5 nm) and thicker, more conductive  $\text{Ta}_2\text{O}_{2-x}$  base layer (~15 nm).
- Top electrode (TE): materials such as Pt, Iridium (Ir), or reactive metals like Ta or Ti.

The use of an Ir electrode sputtered with oxygen creates a smoother TE/oxide interface, suppressing filamentary switching and promoting more uniform, area-based valence change mechanisms [5].

*Switching Mechanism:* The resistive switching in TaOx devices is governed by the migration of oxygen ions and vacancies under an applied electric field. The process involves:

1. SET operation: Applying negative voltage drives oxygen vacancies from the base layer into the insulating layer, forming a conductive filament (CF) and transitioning to Low Resistance State (LRS).
2. RESET operation: Applying positive voltage repels vacancies back into the base layer, rupturing the filament and returning to High Resistance State (HRS).

Lee et al. demonstrated that TaOx devices can achieve fast switching (<10 ns) with endurance exceeding  $10^9$  cycles and retention greater than 10 years at 85°C [5].

## 2.3 Engineering the Third State

The creation of a stable, non-volatile third state ("Null" or "Balance") hinges on precise control of filament formation or rupture. Instead of fully forming a thick, low-resistance filament (LRS) or completely rupturing it (HRS), the "Null" state is an intermediate resistance level achieved through Partial Reset (controlled reset voltage that only partially oxidizes the conductive filament) or Controlled SET.

The stability of this third state requires a wide hysteresis window providing clear separation between three states, high energy barriers preventing spontaneous transitions due to thermal fluctuations, and low resistance drift over time.

### 3. THE EMULATION TAX: QUANTIFIED ANALYSIS

Implementing ternary logic on a binary CMOS substrate incurs a significant "emulation tax." This section provides rigorous quantification of this overhead.

#### 3.1 Encoding Strategies and Overhead

When ternary logic is emulated on binary hardware, three states must be mapped onto binary representations. A 2-bit encoding (representing states 0,1,2 as 00,01,10) immediately doubles the memory footprint compared to native ternary storage. Knuth's analysis of balanced ternary demonstrates mathematical advantages including simplified arithmetic operations [6]. However, emulation on binary hardware requires specialized circuits that negate these benefits due to conversion overhead.

#### 3.2 Logic Gate Inflation

A critical component of the emulation tax is the "logic gate inflation factor"—the ratio of binary gates required to implement a ternary function versus a binary equivalent. Research indicates that a ternary computer may require approximately 1.62 times as much logic in its arithmetic units as a comparable binary computer [6]. However, when emulating on binary hardware, the inflation factor is substantially higher due to decoding logic for multi-bit inputs and complex combinational logic.

#### 3.3 Numerical Analysis: Energy Tax

We model the energy consumption using  $E = aCV^2$ .

- **Baseline Binary MAC:** ~5 fJ per operation.
- **Emulated Ternary MAC:**
  - Logic component (10x gate inflation): ~70 fJ.
  - Memory traffic overhead (2-bit encoding): ~6000 fJ.
  - **Total Emulated Energy:** ~6070 fJ.

**Energy Tax Factor:** The ratio of Emulated Energy (6070 fJ) to Binary Energy (5 fJ) results in a tax of approximately **15.2x**.

#### 3.4 Numerical Analysis: Latency Tax

- **Binary MAC Latency:** 1 cycle.
- **Emulated Ternary MAC Latency:** Logic propagation (5 cycles) + Control path overhead (0.2 cycles) = 5.2 cycles.

**Latency Tax Factor:** The ratio of Emulated Latency to Binary Latency results in a tax of **5.2x**.

## 4. SYSTEM ARCHITECTURE AND THE "SAINT SPOT"

The "Saint Spot" refers to the specific market gap where Mandated Ternary provides fundamental advantages unattainable through binary scaling.

### 4.1 Problem-Mechanism Mapping

- **Interconnect Delay:** Addressed by Dense non-volatile memory + Compute-in-Memory (CiM). Advantage: Eliminates long data movement.
- **Memory Wall:** Addressed by High-density ternary storage. Advantage: 1.58x density increase.
- **Power Density:** Addressed by Low-switching energy devices. Advantage: pJ-level operation energy.
- **SRAM Scaling:** Addressed by Alternative state storage. Advantage: Replaces 6T cell with 1 memristor.

Sebastian et al. provide comprehensive analysis of memory devices for in-memory computing, demonstrating that memristor crossbars can perform matrix-vector multiplication with  $O(1)$  time complexity regardless of matrix size [7].

### 4.2 Agentic AI as Catalyst

The emergence of agentic AI—systems operating in closed-loop perception-planning-action cycles—creates critical requirements for Hesitation Gating (the "Null" state represents uncertainty) and Human-in-the-loop controls. The hardware-enforced "Null" state provides tamper resistance and non-spoofability impossible with software flags, creating an auditable chain of trust from hardware to application layer.

## 5. ROADMAP TO 2027 AND FALSIFIABILITY

### 5.1 Candidate Architectures

1. **Memristor Compute-in-Memory (CiM):** Target: 10 TOPS/W improvement over GPUs by Q4 2026.
2. **Spintronic MTJ Logic:** Target: 5x power-delay product improvement by Q4 2026.
3. **Ferroelectric FETs (FeFET):** Target: 2x density vs. SRAM by Q4 2026.

### 5.2 Falsifiable Predictions (to be validated by Q2 2026)

- TaOx memristor with stable intermediate state: retention >10 years at 85°C, endurance > $10^9$  cycles.
- Coefficient of variation for intermediate state: <10%.

### 5.3 Failure Conditions (would disprove thesis)

- Inability to engineer stable third state with retention >1 year.
- Variability >50% preventing reliable sensing.
- Demonstrated emulation tax <2x in production systems.

## 6. CONCLUSION

This paper has established that the physics of memristive hysteresis enables a stable, non-volatile third state in TaO<sub>x</sub> devices [5], and that emulation of ternary logic on binary hardware incurs fundamental penalties exceeding 15x in energy. The transition to Mandated Ternary is not merely an academic exercise but a necessary evolution. The physical limits of binary scaling, combined with emerging requirements for safe autonomous systems, create conditions where this paradigm shift becomes inevitable if technical milestones are achieved.

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